TOSHIBA BIPOLAR DIGITAL INTEGRATED CIRCUIT SILICON MONOLITHIC

# ULN2003AP,ULN2003AFW,ULN2004AP,ULN2004AFW (Manufactured by Toshiba Malaysia)

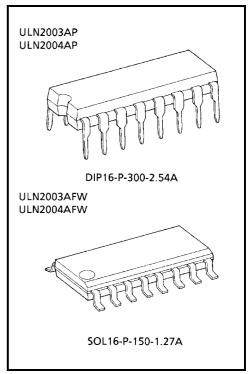
#### 7CH DARLINGTON SINK DRIVER

The ULN2003AP / AFW Series are high-voltage, high-current darlington drivers comprised of seven NPN darlington pairs. All units feature integral clamp diodes for switching inductive loads.

Applications include relay, hammer, lamp and display (LED) drivers.

#### **FEATURES**

- Output current (single output) 500 mA MAX.
- High sustaining voltage output 50 V MIN.
- Output clamp diodes
- Inputs compatible with various types of logic
- Package Type-AP : DIP-16pinPackage Type-AFW : SOL-16pin

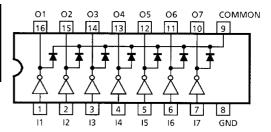


Weight

DIP16-P-300-2.54A : 1.11 g (Typ.) SOL16-P-150-1.27A : 0.15 g (Typ.)

#### **PIN CONNECTION (TOP VIEW)**

TYPE	INPUT BASE RESISTOR	DESIGNATION
ULN2003AP / AFW	2.7 kΩ	TTL, 5 V CMOS
ULN2004AP / AFW	10.5 kΩ	6~15 V PMOS, CMOS



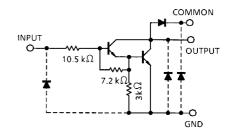


#### **SCHEMATICS (EACH DRIVER)**

ULN2003AP / AFW

# COMMON OUTPUT 7.2 kΩ C M GND

#### ULN2004AP / AFW



Note: The input and output parasitic diodes cannot be used as clamp diodes.

# MAXIMUM RATINGS (Ta = 25°C)

CHARACTERISTIC		SYMBOL	RATING	UNIT	
Output Sustaining Voltage		V <sub>CE (SUS)</sub>	-0.5~50	V	
Output Current		lout	500	mA / ch	
Input Voltage		V <sub>IN</sub>	-0.5~30	V	
Clamp Diode Reverse Voltage		V <sub>R</sub>	50	٧	
Clamp Diode Forward Current		l <sub>F</sub>	500	mA	
	AP		1.47	W	
Power Dissipation	AFW	P <sub>D</sub>	0.54 / 0.625 (Note)		
Operating Temperature		T <sub>opr</sub>	-40~85	°C	
Storage Temperature		T <sub>stg</sub>	tg -55~150		

Note: On glass epoxy PCB (30 × 30 × 1.6 mm Cu 50%)



# RECOMMENDED OPERATING CONDITIONS (Ta = -40~85°C)

CHARACTE	ERISTIC	SYMBOL	TEST CONDITION		MIN	TYP.	MAX	UNIT	
Output Sustaining Volta	utput Sustaining Voltage V <sub>CE (SUS)</sub>			0	_	50	V		
Output Current	AP	- Іоит	T <sub>pw</sub> = 25 ms	Duty = 10%	0	_	370		
			7 Circuits	Duty = 50%	0	_	130	mA / ch	
	AFW		Ta = 85°C	Duty = 10%	0	_	233		
			T <sub>j</sub> = 120°C	Duty = 50%	0	_	70		
Input Voltage		V <sub>IN</sub>			0	_	24	V	
Input Voltage (Output On)	ULN2003A	V	I <sub>OUT</sub> = 400 mA h <sub>FE</sub> = 800		2.8	_	24	V	
	ULN2004A	V <sub>IN</sub> (ON)			6.2	_	24		
Input Voltage (Output Off)	ULN2003A	V			0	_	0.7	V	
	ULN2004A	V <sub>IN</sub> (OFF)			0	_	1.0	V	
Clamp Diode Reverse Voltage		V <sub>R</sub>			_	_	50	V	
Clamp Diode Forward Current		I <sub>F</sub>			_	_	350	mA	
Power Dissipation	AP	D-	Ta = 85°C		_	_	0.76	W	
	AFW	P <sub>D</sub>	Ta = 85°C	(Note)	_	_	0.325	VV	

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Note: On glass epoxy PCB (30 × 30 × 1.6 mm Cu 50%)

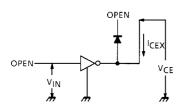


# **ELECTRICAL CHARACTERISTICS (Ta = 25°C unless otherwise noted)**

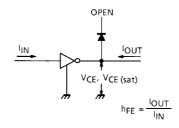
CHARACTE	RISTIC	SYMBOL	TEST CIR- CUIT	TEST CONDITION		MIN	TYP.	MAX	UNIT
Output Lasks as Output		1	1	V <sub>CE</sub> = 50 V, Ta = 25°C		_	_	50	
Output Leakage Current		I <sub>CEX</sub>		V <sub>CE</sub> = 50 V, Ta = 85°C		_	_	100	μA
Collector-Emitter Saturation Voltage			2	I <sub>OUT</sub> = 350 mA, I <sub>IN</sub> = 500 μA		_	1.3	1.6	٧
		V <sub>CE (sat)</sub>		I <sub>OUT</sub> = 200 r	I <sub>OUT</sub> = 200 mA, I <sub>IN</sub> = 350 μA		1.1	1.3	
				I <sub>OUT</sub> = 100 mA, I <sub>IN</sub> = 250 μA		_	0.9	1.1	
DC Current Transfer I	Ratio	h <sub>FE</sub>	2	V <sub>CE</sub> = 2 V, I <sub>OUT</sub> = 350 mA		1000	_	_	
Input Current	ULN2003A		_	V <sub>IN</sub> = 2.4 V, I <sub>OUT</sub> = 350 mA		_	0.4	0.7	mA
(Output On)	ULN2004A	I <sub>IN (ON)</sub>	3	V <sub>IN</sub> = 9.5 V, I <sub>OUT</sub> = 350 mA		_	0.8	1.2	
Input Current (Output Off)		I <sub>IN (OFF)</sub>	4	I <sub>OUT</sub> = 500 μA, Ta = 85°C		50	65	_	μA
	ULN2003A	Vin (ON)	5	V <sub>CE</sub> = 2 V h <sub>FE</sub> = 800	I <sub>OUT</sub> = 350 mA	_	_	2.6	V
Input Voltage					I <sub>OUT</sub> = 200 mA	_	_	2.0	
(Output On)	ULN2004A				I <sub>OUT</sub> = 350 mA	_	_	4.7	
					I <sub>OUT</sub> = 200 mA	_	_	4.4	
Clamp Diode Reverse Current			6	V <sub>R</sub> = 50 V, Ta = 25°C		_	_	50	
		I <sub>R</sub>		V <sub>R</sub> = 50 V, Ta = 85°C		_	_	100	μA
Clamp Diode Forward Voltage		V <sub>F</sub>	7	I <sub>F</sub> = 350 mA		_	_	2.0	V
Input Capacitance		C <sub>IN</sub>	_			_	15	_	pF
Turn-On Delay		ton	8	$V_{OUT}$ = 50 V, $R_{L}$ = 125 $\Omega$ $C_{L}$ = 15 pF		_	0.1	_	us
Turn-Off Delay		t <sub>OFF</sub>	8	$V_{OUT}$ = 50 V, $R_{L}$ = 125 $\Omega$ $C_{L}$ = 15 pF		_	0.2	_	μσ

#### **TEST CIRCUIT**

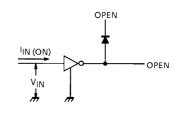
# 1. I<sub>CEX</sub>



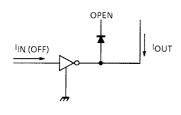
# 2. V<sub>CE (sat),</sub> h<sub>FE</sub>



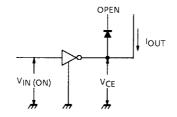
# 3. I<sub>IN (ON)</sub>



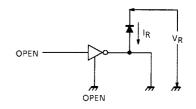
#### 4. In (OFF)



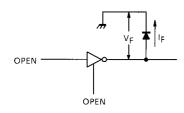
#### 5. V<sub>IN (ON)</sub>



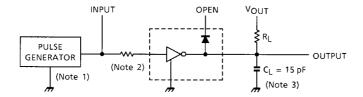
# 6. I<sub>R</sub>

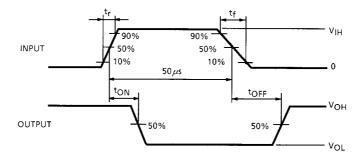


# 7. V<sub>F</sub>



#### 8. ton, toff





Note 1: Pulse width 50 µs, duty cycle 10%

Output impedance 50  $\Omega$ ,  $t_f \le 5$  ns,  $t_f \le 10$  ns

Note 2: See below

#### INPUT CONDITION

TYPE NUMBER	R1	V <sub>IH</sub>					
ULN2003AP / AFW	0	3 V					
ULN2004AP / AFW	0	8 V					

Note 3: C<sub>L</sub> includes probe and jig capacitance.

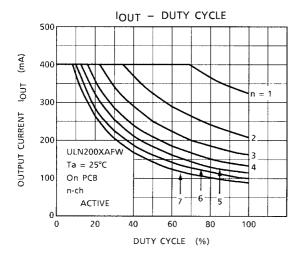
#### **PRECAUTIONS for USING**

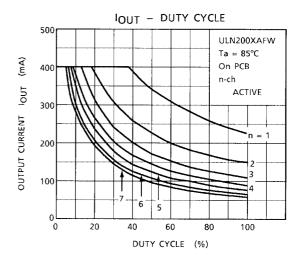
This IC does not include built-in protection circuits for excess current or overvoltage.

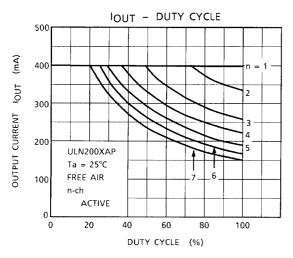
If this IC is subjected to excess current or overvoltage, it may be destroyed.

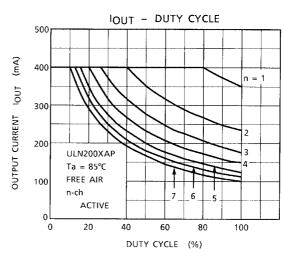
Hence, the utmost care must be taken when systems which incorporate this IC are designed.

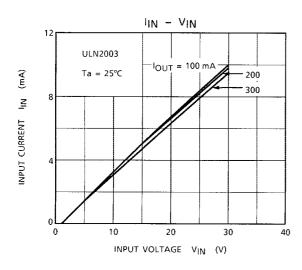
Utmost care is necessary in the design of the output line, COMMON and GND line since IC may be destroyed due to short-circuit between outputs, air contamination fault, or fault by improper grounding.

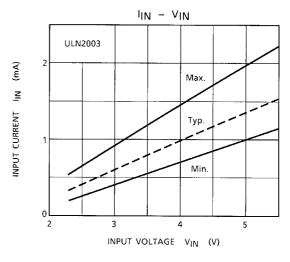


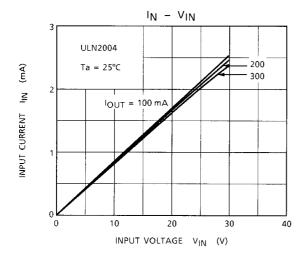


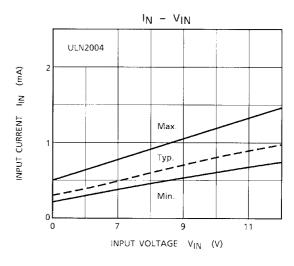


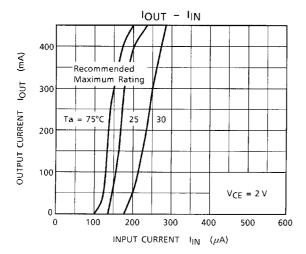


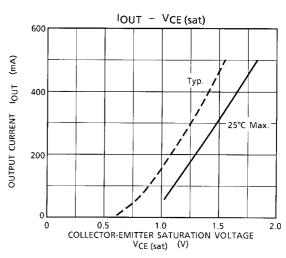


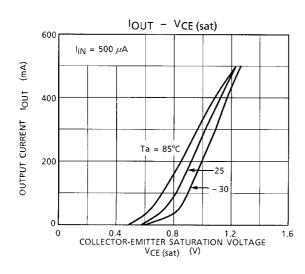


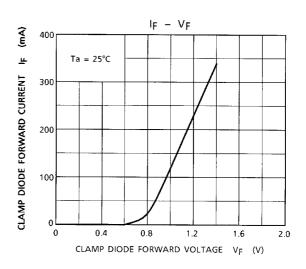


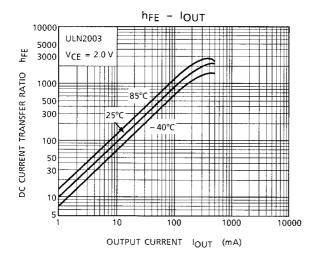


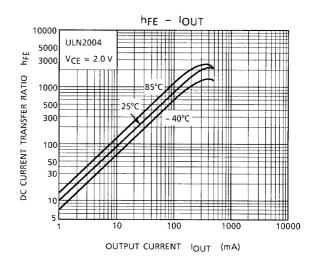


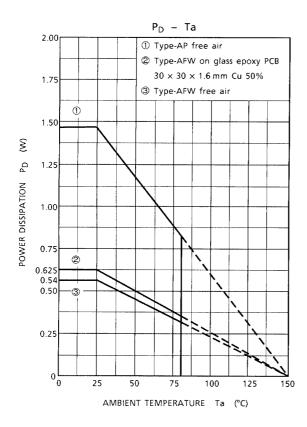








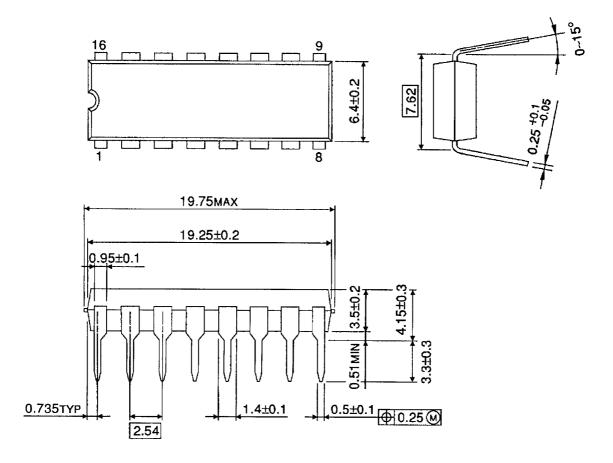






#### **PACKAGE DIMENSIONS**

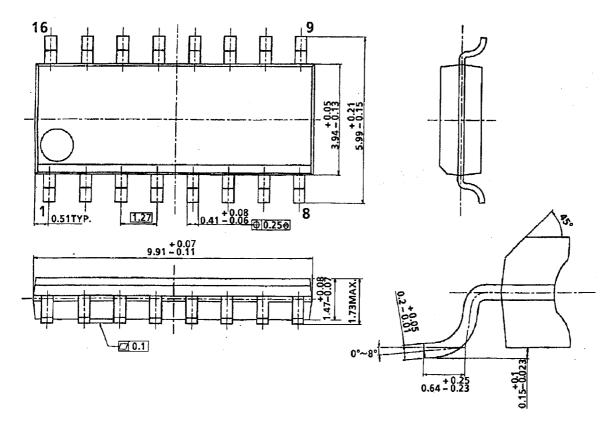
DIP16-P-300-2.54A



Weight: 1.11 g (Typ.)

#### **PACKAGE DIMENSIONS**

SOL16-P-150-1.27A



Weight: 0.15 g (Typ.)

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